

LTM8001 121 LD-BGA-Pb 15mm X 15mm X 3.42mm -EPOXY DA(TABLE OF MATERIAL DECLARATION)

Contains > 1000ppm of Lead in the terminations

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)				
1	Substrate	Circuit Board	0.2486	Barium Compounds	7727-43-7	0.00631	2.54				
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.04723	19.00				
				Copper Metal	7440-50-8	0.14125	56.82				
				Copper Compounds	147-14-8	0.00005	0.02				
				Ecotoxic substances	7440-38-2 7440-28-0	0.00002	0.01				
				Gold metal or alloy	7440-57-5	0.00040	0.16				
				Nickel	7440-02-0	0.00189	0.76				
				Zinc	7440-66-6	0.00027	0.11				
				Continuous Filament Fiber Glass	65997-17-3	0.03712	14.93				
				Acrylic Resin	non-disclosure	0.01203	4.84				
				Epoxy Resin	non-disclosure	0.00005	0.02				
				Chromium (III) oxide	1308-38-9	0.00001	0.00				
				Silica amorphous	7631-86-9	0.00014	0.06				
				Talcinot containing fibers like asbestos	14807-96-6	0.00072	0.29				
				Arcomatic carbonyl compounds	non-disclosure	0.00070	0.28				
				Cyanoguanidine	461-58-5	0.00002	0.01				
				Calcium Caobonate	471-34-1	0.00001	0.00				
				Amine compounds	non-disclosure	0.00009	0.04				
				Leveling agent and others	non-disclosure	0.00027	0.11				
				2	Solder Paste	Alloy	0.0208	Sn	7440-31-5	0.01975	95.00
								Sb	7440-36-0	0.00104	5.00
				3	Epoxy		0.0007	Di-ester resin	-	0.00006	8.00
Functionalized ester	-	0.00006	8.00								
4	Passive/Active Components		0.5253	Silver	7440-22-4	0.00059	84.00				
				Iron Powder (Fe)	7439-89-6	0.35794	68.15				
				Copper (Cu)	7440-50-8	0.10978	20.90				
				Nickel (Ni)	7440-02-0	0.00684	1.30				
				Tin (Sn)	7440-31-5	0.00466	0.89				
5	Active lcs	Silicon	0.0125	Ceramic (Ba) Compounds	12047-27-7	0.04607	8.77				
				Silicon	7440-21-3	0.01247	100.00				
6	Wire	Gold	0.0006	Au	7440-57-5	0.00064	99.99				
6	Solder Ball	63Sn/37Pb	0.2314	Sn	7440-31-5	0.14578	63.00				
				Pb	7439-92-1	0.08562	37.00				
8	Encapsulation	Epoxy Resin	0.8077	Fused Silica	60676-86-0	0.62358	77.20				
				Epoxy Resin	non-disclosure	0.07189	8.90				
				Phenol Resin	non-disclosure	0.07189	8.90				
				Crytalline Silica	14808-60-7	0.02423	3.00				
				Carbon Black	1333-86-4	0.00404	0.50				
				Metal Hydroxide	non-disclosure	0.01212	1.50				
Total Package Weight			1.8476								

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts